

Customer No.: 31561
Docket No.: 10573-US-PA
Application No.: 10/604,793

In The Specification:

Please amend paragraphs [0033] and [0035] as follows:

[0033] Referring to FIG. 1, an ion sampling system 100 for a wafer surface according to the first exemplary embodiment of the present invention includes at least a sampling chamber 102, a wafer carrier shelf beam 104, an extraction liquid spraying apparatus 106, an extraction liquid supply apparatus 108a, a fluid supply apparatus 108b, a cleaning/drying spray nozzle 112, a cleaning solution supply apparatus 114, and a fluid supply apparatus 116. The cleaning/drying spray nozzle 112, the cleaning solution supply apparatus 114 and fluid supply apparatus 116 together constitute a cleaning/drying apparatus.

[0035] The plurality of wafer carrier beams 104, for example, is disposed on and dispersedly arranged around the upper part of the sampling chamber 102. Each of the wafer carrier beams 104 is, for example, bar-shaped, wherein one end of the wafer carrier beam 104 is extended to the outside of the sampling chamber 102, allowing the wafer carrier beam 104 to rotate freely. A rotating handle 104a is disposed on the extended end of the wafer carrier beam 104. A wafer anchoring pin 104b, which extends in one direction, is disposed on a peripheral surface of the wafer carrier beam 104. Another wafer anchoring pin 104c, which is extended in a different direction, forms at least a 90 degrees angle with the wafer anchoring pin 104b. The wafer carrier beam 104, therefore, can at most include four sets of wafer anchoring pins. The wafer anchoring pin 104b, for example, is used to firmly hold a wafer of a larger dimension (for example, a 12 inch wafer), whereas the wafer anchoring pin 104c, for example, is used to firmly hold a wafer of

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a smaller dimension (for example, an 8 inch wafer). In this exemplary embodiment, there are at least three wafer carrier beams. Further, the height of one wafer ~~carrier beam~~ carrier beam 104 is lower than the heights of other wafer carrier beams 104. As a result, the wafer 110 can be tilted at an angle θ when the wafer 110 is placed on the wafer carrier beams 104.